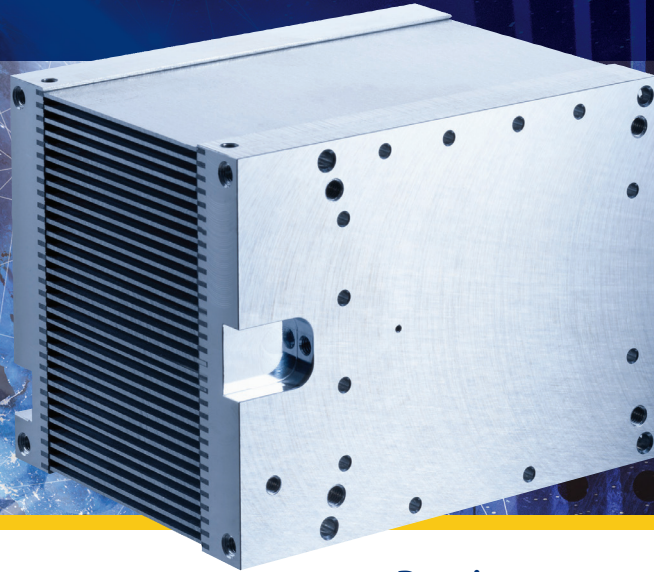


AIR COOLING

Series Copper Standard SF



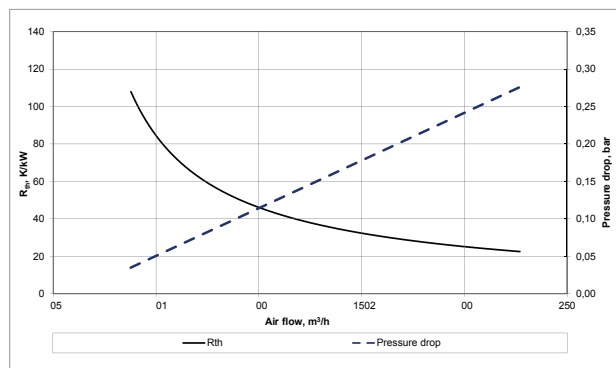
Application

Customized copper Heat Sinks for efficient air cooling of IGBTs and resistors. DAU offers high performance customized solutions for all IGBT and resistor types available on the market.

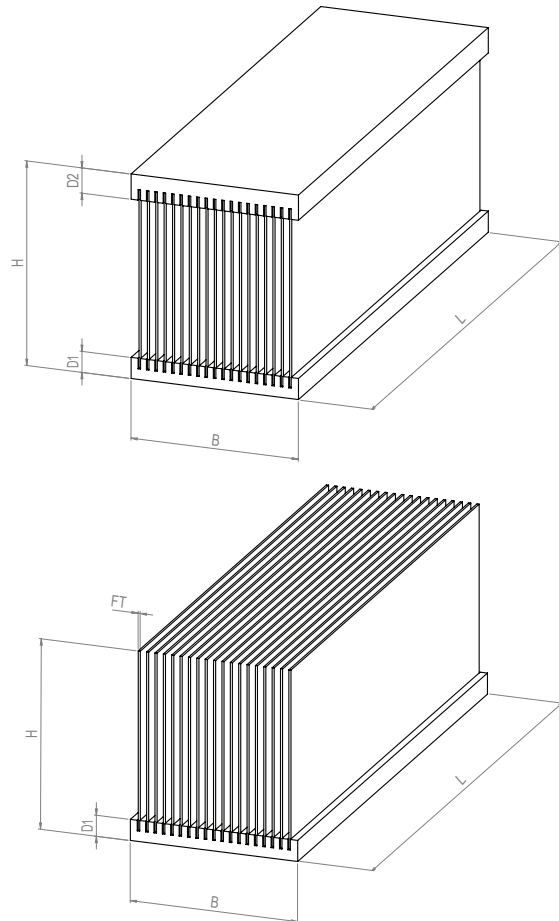
General Characteristics

DAU Series SF is used for extremely high power IGBT and resistor applications. The unique solder technique creates an excellent interface between the copper baseplate and the copper fins. Due to the thermal conductivity of copper the efficiency is higher than other aluminium types.

	Width B mm	Base- plate D1 mm	Thickness D2 mm	Fin Thickness FT mm	Height H mm	Length L mm
min.	40	8	8	0,5	25	60
max.	300	25	15	2	150	400



Drawings



Description

- No. of modules: 7
- Module size: 68x90 [mm]
- Power dissipation: 140 [W/modul]
- Thermocouple: Type K
- Air inlet temperature: 25[°C]

